

# BL 1005 Series Multilayer Chip Baluns

#### Features

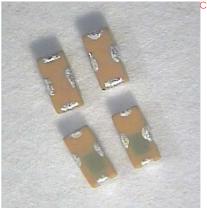
Monolithic SMD with small, low-profile and light-weight type.

✤ RoHS compliant

#### Applications

✤ 758 ~ 821 MHz wireless communication systems.

#### Specifications



Part Number	Frequency Range (MHz)	Unbalanced Impedance (ohm)	Balance Impedance (ohm)	Insertion Loss (dB)	Return Loss (dB)	Phase Difference (degree)	Amplitude Difference (dB)
BL1005- 10D0790	758 ~ 821	50	100	0.8max.	15 min.	180 ± 10	2 max.

Q'ty/Reel (pcs): 10000Operating Temperature Range: -40 ~ +85 °CStorage Temperature Range: -40 ~ +85 °CStorage Period: 12 months max.\*\*12 months in vacuum sealed bagand 1 week after opened. Please keep unused parts in vacuum sealed bags.Solder Paste: SAC 305 type is recommended.Power Capacity: 3W max.

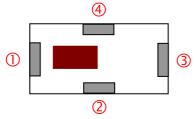
#### Part Number

<u>BL</u>	<u>1005</u>	-	<u>10</u>	<u>D</u>	<u>0790</u>		<u>/LF</u>
1	2		3	4	(5)	6	$\bigcirc$

① Туре	BL : Balun	② Dimensions (L×W)	1.0 × 0.5 mm	
3 Balun Impedance	10:100 ohnm	Specification Code	D	
S Frequency Range	0790=790MHz	6 Packaging	T: Tape & Reel B: Bulk	
Soldering	/LF=lead-free			



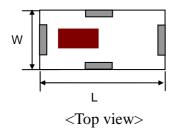
### **Terminal Configuration**



No.	Terminal Name	No.	Terminal Name
0	Balanced Port	3	Balanced Port
2	Unbalanced Port	4	GND

#### Dimensions and Recommended PC Board Pattern

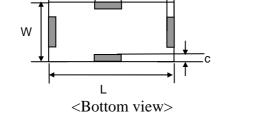
Unit : mm



а

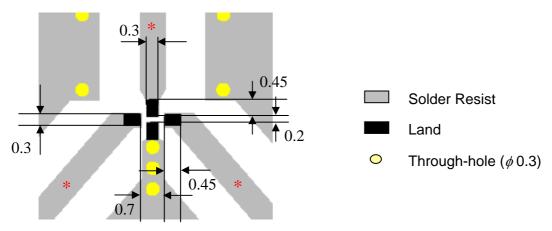


<Side view>



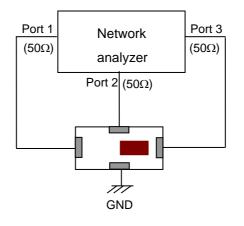
Mark	L	W	Т	а	b	С	d
Dimensions	1.0 ±	0.5 ±	0.38±	0.3±	0.3±	0.1±	0.35±
Dimensions	0.1	0.05	0.05	0.10	0.10	0.05	0.1



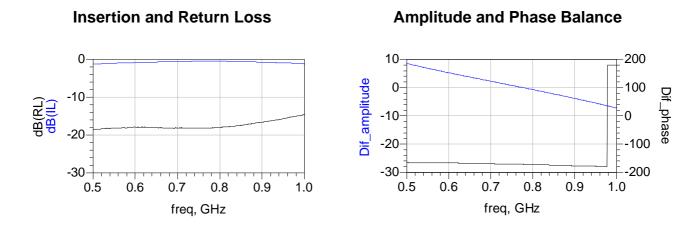


\* Line width should be designed to match  $50\Omega$  characteristic impedance, depending on PCB material and thickness.

#### **Measuring Diagram**



#### Typical Electrical Characteristics (T=25°C)



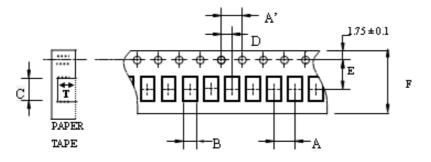
#### Notes

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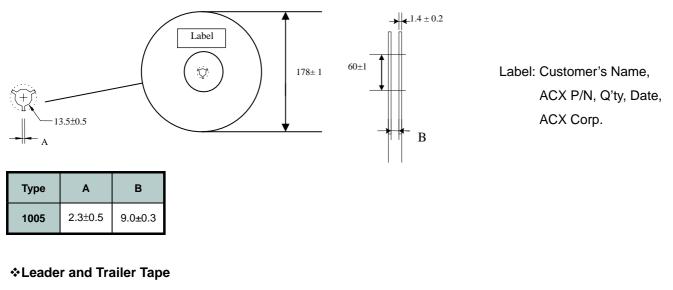
#### **Taping Specifications**

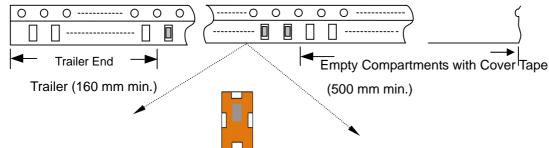
#### ✤Tape Dimensions (Unit: mm) & Quantity



Туре	Α	A'	В	С	D	E	F	т	Quantity/reel	Tape material
1005	2.0±	4.0±	0.62±	1.12±	2.0±	3.5±	8.0±	0.45±	10,000	Dopor
1005	0.05	0.1	0.03	0.03	0.05	0.05	0.1	0.03	10,000pcs	Paper

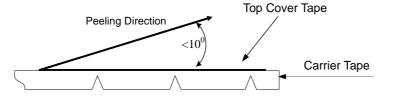
#### Reel Dimensions (Unit: mm)







#### \*Peel-off Force



Peel-off force should be in the range of 0.1 - 0.6 N at a peel-off speed of  $300\pm10$  mm/min .

#### Storage Conditions

- (1) Temperature:  $5 \sim 35^{\circ}$ C, relative humidity (RH):  $45 \sim 75$ %.
- (2) Non-corrosive environment.

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### Mechanical & Environmental Characteristics

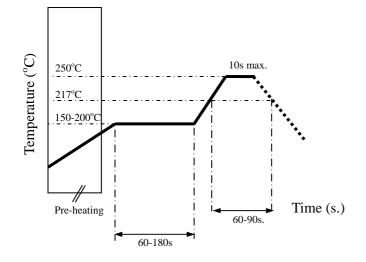
Item	Requirements	Procedure
Solderability	<ol> <li>No apparent damage</li> <li>More than 75% of the terminal electrode shall be covered with new solder.</li> </ol>	<ol> <li>Preheat: 120± 5 °C</li> <li>Solder: 245± 5 °C for 5± 1 sec</li> </ol>
Soldering strength (Termination Adhesion)	1. 3N minimum	<ol> <li>Solder specimen onto test jig.</li> <li>Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	<ol> <li>No apparent damage</li> <li>Fulfill the electrical specification</li> </ol>	<ol> <li>Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>Apply a bending force of 2mm deflection         Pressure Rod         R230         Pressure Rod         90mm         90mm         </li> </ol>
Heat/Humidity Resistance	<ol> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol> <li>Temperature: 85± 2°C</li> <li>Humidity: 90% ~ 95% RH</li> <li>Duration: 1000±48hrs</li> <li>Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	<ol> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol> <li>One cycle/step 1 : 125 ± 5°C for 30 min step 2 : - 40 ± 5°C for 30 min</li> <li>No of cycles : 100</li> <li>Recovery:1-2 hrs</li> </ol>
Low Temperature Resistance	<ol> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol> <li>Temperature: -40± 5 °C</li> <li>Duration: 500 ±24hrs</li> <li>Recovery: 1-2hrs</li> </ol>



#### Soldering Conditions

#### **\***Typical Soldering Profile for Lead-free Process

**Reflow Soldering :** 



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Advanced Ceramic X Corp. 16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan TEL:886-3-5987008 FAX:886-3-5987001 E-mail: acx@acxc.com.tw http://www.acxc.com.tw

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